

Title (en)  
WAFER DE-CHUCKING

Title (de)  
LÖSEN VON WAFERN

Title (fr)  
DE-CHUCKING DE PLAQUETTE

Publication  
**EP 2024136 A2 20090218 (EN)**

Application  
**EP 07735709 A 20070430**

Priority  
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Abstract (en)  
[origin: WO2007125511A2] A carrier head (100) for a CMP tool, wherein the membrane (108) defining a chamber with a contact surface (102) of the carrier head (100) has a number of integral tubes (110) terminating in openings coupled directly to the substrate (106), in addition to a main fluid flow passage (104) coupled to the chamber defined by the membrane (108). In use, during loading and polishing, a vacuum is applied to the main fluid flow passage (104) and the tubes (110) to hold the substrate (106) in flat engagement with the membrane (108) and contact surface (102). In order to unload the substrate (106), fluid pressure is applied to the substrate (106) via the tubes (110), whilst maintaining the application of the vacuum via the main fluid flow passage (104) so as to minimise bending and breakage of the substrate (106).

IPC 8 full level  
**B24B 37/30** (2012.01)

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Citation (search report)  
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